

2SC5543

Silicon NPN Epitaxial VHF / UHF wide band amplifier

REJ03G0745-0200
(Previous ADE-208-690)
Rev.2.00
Aug.10.2005

Features

- Super compact package; $(1.4 \times 0.8 \times 0.59 \text{mm})$
- Capable low voltage operation ;
 - $(V_{CE} = 1V)$

Outline



Absolute Maximum Ratings

			$(Ta = 25^{\circ}C)$
Item	Symbol	Ratings	Unit
Collector to base voltage	V _{CBO}	15	V
Collector to emitter voltage	V _{CEO}	8	V
Emitter to base voltage	V _{EBO}	1.5	V
Collector current	Ι _C	20	mA
Collector power dissipation	Pc	80	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

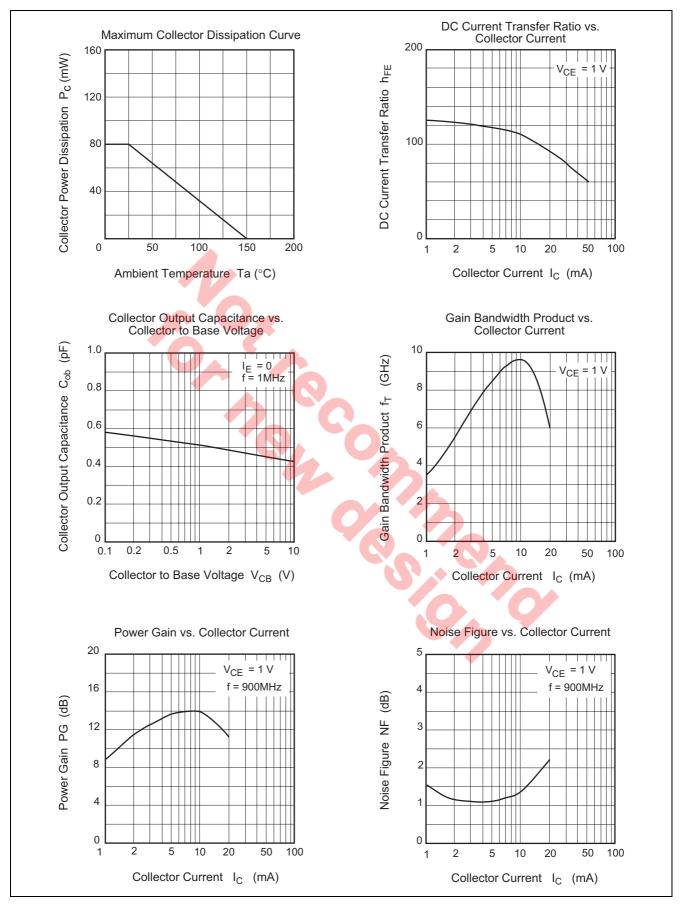


Electrical Characteristics

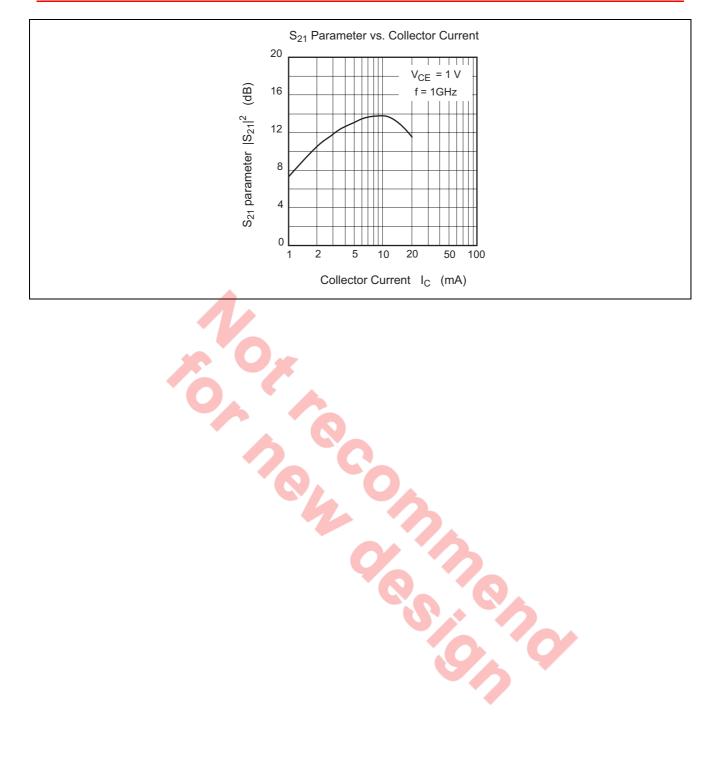
						$(Ta = 25^{\circ}C)$
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Collector cutoff current	I _{CBO}	_		10	μA	$V_{CB} = 15V$, $I_E = 0$
Collector cutoff current	I _{CEO}	_		1	mA	$V_{CE} = 8V$, $R_{BE} = \infty$
Emitter cutoff current	I _{EBO}	_	_	10	μA	$V_{EB} = 1.5V$, $I_C = 0$
DC current transfer ratio	h _{FE}	85	_	170		$V_{CE} = 1V$, $I_C = 5mA$
Collector output capacitance	Cob	_	0.51	0.9	pF	$V_{CB} = 1V$, $I_E = 0$
						f = 1MHz
Gain bandwidth product	f _T	5.5	8.5	—	GHz	$V_{CE} = 1V$, $I_C = 5mA$
Power gain	PG	11	13.7	—	dB	$V_{CE} = 1V$, $I_C = 5mA$
						f = 900MHz
Noise figure	NF		1.1	2.5	dB	$V_{CE} = 1V$, $I_C = 5mA$
						f = 900MHz



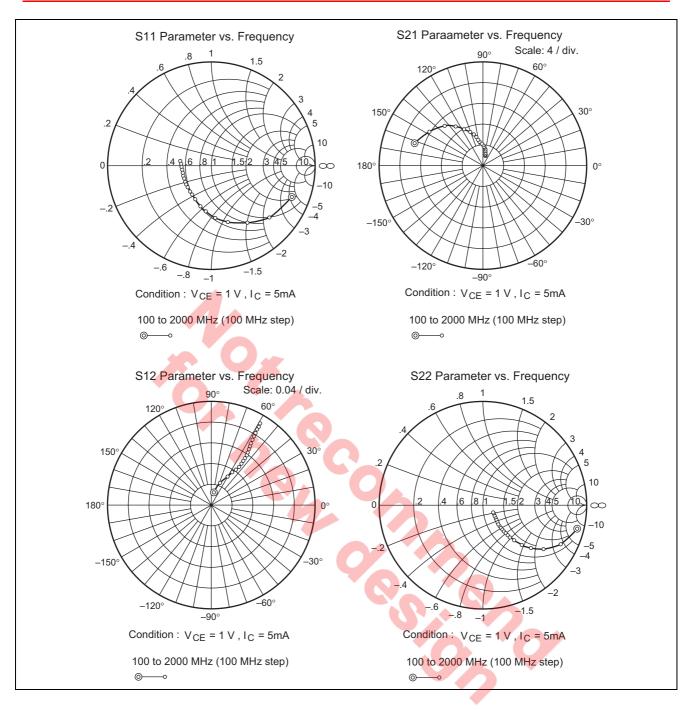
Main Characteristics









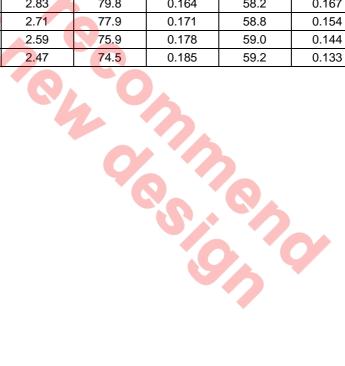




Sparameter

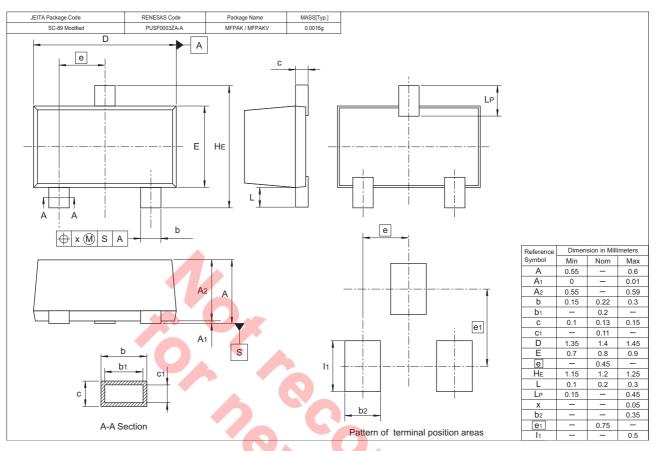
 $(V_{CE} = 1V, I_C = 5mA, Zo = 50\Omega)$

	S	11	S	21	S	12	S	22
f (MHz)	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
100	0.836	-20.7	13.66	162.9	0.0249	77.4	0.948	-14.2
200	0.757	-41.1	12.22	146.9	0.0472	68.0	0.846	-26.9
300	0.649	-58.5	10.57	134.1	0.0637	60.8	0.727	-36.2
400	0.564	-73.2	9.14	124.5	0.0750	56.9	0.623	-42.5
500	0.496	-85.2	7.90	116.8	0.0840	54.2	0.538	-46.2
600	0.436	-97.1	6.91	111.2	0.0916	53.4	0.469	-48.8
700	0.396	-106.2	6.12	105.9	0.0985	53.0	0.413	-50.4
800	0.364	-114.9	5.49	102.0	0.105	53.2	0.368	-51.1
900	0.338	-123.9	4.96	98.3	0.111	53.6	0.327	-51.1
1000	0.316	-130.6	4.52	95.3	0.118	54.1	0.297	-51.2
1100	0.305	-140.0	4.16	92.3	0.124	54.7	0.270	-50.7
1200	0.296	-146.5	3.86	89.8	0.130	55.3	0.246	-49.7
1300	0.293	-153.0	3.59	87.5	0.137	56.1	0.229	-48.7
1400	0.286	-159.5	3.36	85.4	0.143	56.6	0.209	-47.9
1500	0.287	-166.0	3.17	83.2	0.150	57.2	0.195	-46.3
1600	0.285	-170.7	3.00	81.4	0.157	57.7	0.180	-45.0
1700	0.289	-175.8	2.83	79.8	0.164	58.2	0.167	-43.8
1800	0.294	178.7	2.71	77.9	0.171	58.8	0.154	-42.4
1900	0.302	175.4	2.59	75.9	0.178	59.0	0.144	-40.2
2000	0.308	171.1	2.47	74.5	0.185	59.2	0.133	-38.6





Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SC5543YA-TR-E	9000	

0

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



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